

# SOT865-1

plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 7 x 7 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN32
<b>Package type industry code</b>	HVQFN32
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	20-9-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A <sub>2</sub>	package height	[tbd]	-	0.85	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	32	-	

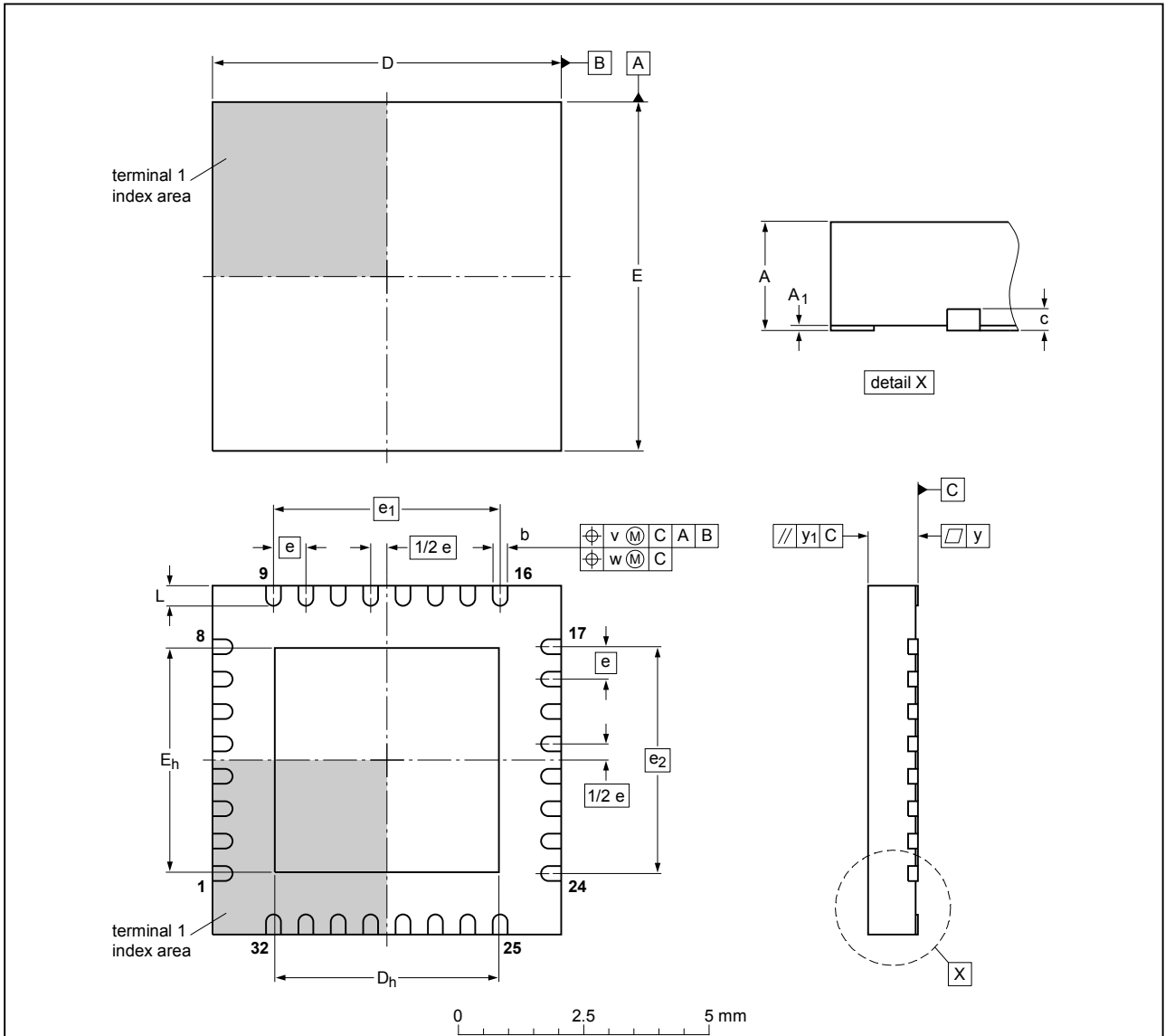


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## 2. Package outline

HVQFN32: plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body 7 x 7 x 0.85 mm

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sup>(1)</sup> max	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.35 0.25	0.2	7.1 6.9	4.6 4.4	7.1 6.9	4.6 4.4	0.65	4.55	4.55	0.5 0.3	0.1	0.1	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT865-1	---	MO-220	---		04-09-08 04-09-20

Fig. 1. Package outline HVQFN32 (SOT865-1)

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0.85 mm

### 3. Legal information

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